



CBR-SMD RF COG, Ceramic, 0.9 pF, +/-0.05 pF, 100 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0402



General Information	
Series	CBR-SMD RF COG
Style	SMD Chip
Description	SMD, Fixed, RF, Ultra High Q, Low ESR, Class I
Features	Ultra High Q, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	1.37 mg
Notes	Solder Reflow Only.
Shelf Life	78 Weeks
MSL	1

0.9 pF

Dimensions	
Chip Size	0402
L	1mm +/-0.05mm
W	0.5mm +/-0.05mm
Т	0.5mm +/-0.05mm
В	0.25mm +0.05/-0.1mm

L	1mm +/-0.05mm	Tolerance	+/-0.05 pF
W	0.5mm +/-0.05mm	Voltage DC	100 VDC
T	0.5mm +/-0.05mm	Dielectric Withstanding Voltage	250 VDC
B 0.25mm +0.05/-0.1mm		Temperature Range	-55/+125°C
		Temp. Coefficient	COG
Packaging Specifications		Dissipation Factor	0.239%
Packaging	T&R, 180mm, Plastic Tape	Aging Rate	0% Loss/Decade Hour
Packaging Quantity 10000	10000	Insulation Resistance	10 GOhms
		Quality Factor	418

Specifications

Capacitance

	0.20	
		Temp. Coefficie
Packaging Specifications		Dissipation Fac
Packaging	T&R, 180mm, Plastic Tape	Aging Rate
Packaging Quantity	10000	Insulation Resis
		Quality Factor

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